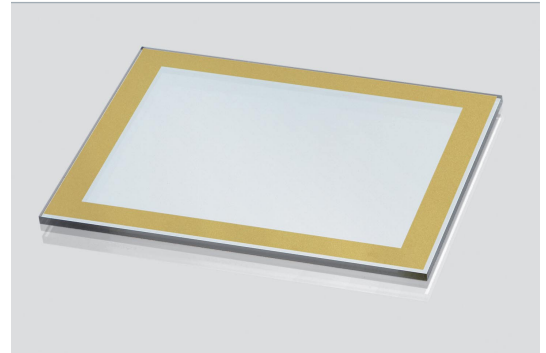


## Patterned Gelot™ for Advanced Optical Packaging

### Solderable Glass Lids

Light sensitive semiconductor devices require a packaging including a transparent glass lid. Soldering the lids provides the best hermeticity values of such packagings. Gelot™ solderable coating gives the glass a surface which adheres to solder such as Gold or Palladium. Gelot™ is applied to the lid in the form of a frame with a clear aperture.

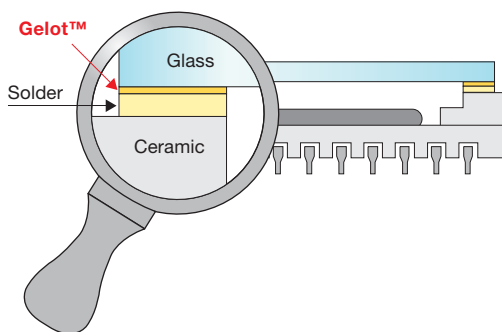


### Benefits

- Soldering of glass to metals and ceramics
- Excellent hermeticity values in assemblies with glass lids
- Suitable for high temperature applications
- Excellent shelf life values due to non-corrosive surface
- Frames may be used as apertures
- Allows clean assembly process
- Wafer Level Packaging (WLP) can be supported
- Can Serve as a busbar

### Soldered Assembly

The Gelot™ Coating provides the glass a solderable surface. The solder itself must be applied in a preform.



### Applications

Packaging of semiconductor devices such as CCD/CMOS sensors, MEMS.

### Technical Data

#### Outer surface coating

Gold

#### Thickness of coating

300nm

#### Minimum feature size of coating

20 μm

#### Size of Lids

up to 120 mm sq

#### Adhesion

> 10 N/mm<sup>2</sup>

#### Shear strength

> 4 N/mm<sup>2</sup>

### Recommendations

Solderable preform: Au, Pd (Al, Zn or Cd to be avoided)  
Stencilled AR on clear aperture

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